PRECAUTION IN USE

1. Soldering Condition

◎ Keep minimum clearance between the resin and the soldering point when soldering.

◎ Maximum allowable soldering conditions are:

Solder dipping: 260° C max., 5 seconds max., one time

Soldering Iron: 350° C max., 5 seconds max., one time, power 40W max.

◎ Contact between molten solder and the resin must be avoided.

◎ In soldering, do not put any stress to the lead frame, particularly when heated.

◎ Maximum allowable soldering conditions for the LED and other SMD parts on the same circuit board and adhesive is to be cured, are: 120° C max., 60 seconds max.

2. Lead forming and cutting

◎ Lead forming must be performed below the tie bar cutting portion and the process must be before soldering.

◎ Do not put stress on the resin case when forming/cutting a lead.

◎ Do not cut the lead frame at high temperature which may cause quality problems.

3. Assembly

◎ Do not put stress to the lead frame when assembling.

◎ The pitch between the mounting holes should match with that of the LED when mounting onto PCBs.

4. Static Electricity

◎ The users are required to hand the LED with care as they are so sensitive to static electricity.

◎ A protection device should be installed in the LED driving circuit which does not exceed the maximum rating for surge current during on/off switching.

◎ Proper grounding of the LED (via 1 MΩ), use of conductive mat/ semi-conductive working uniform/ shoes/ containers are considered to be effective as countermeasures against static electricity and surge.

◎ A tip of soldering iron is required to be grounded. An ionizer should also be installed where risk of static generation is high.

5. Safety Precautions

◎ The light output of the LED may cause injuries to human eyes in the circumstances where the LED is viewed directly for more than a few seconds.